ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES®	© Co	terial Compo pyright 2005. IPC, Bannoci nternational and Pan-Americ	kburn, Illinois	. All rights reserve	tion with lowe	r level p	parts, the	declaration	encon	npasses a	all lower le	evel mate	erials for	which th	item is an assembly e manufacturer has eclaration.	
1752-2 1.1		Web Site for Informat		-1752 Standa		Form Type * Declaration Class * Distribute Class 6 - RoHS Yes/No, Homogeneous Material							laterials	and Mfg Informat		
Supplier Information																
Company Name * Company Unique ID				Unique ID Authority			Response Date *				Response Document ID					
RAMI TECHNOLOGY USA L							2021									
Contact Name * Title - Contact				Phone - Contact *			- Contac	t *		D	-1:4- 0	\44	> A41	.: I D -		
YG Jiao	QA manager		0755-215371	ygjiao@ramitechnology.com				Dup	olicate C	ontact	-> Autno	rizea Re	presentative			
Authorized Representative * Title - Representative			e	Phone - Representative *			- Represe	entative *	+ (Supplier (Comments	s or UR	L for Add	itional In	formation	
Frank Parra	Frank Parra QA manager			305-593-6033			@ramitec	hnology.	com							
Requester Item Number	er	Mfr Item Number		Mfr Item Name		Effectiv	ve Date	Version	Manufa	ufacturing Site		eight *	UC	М	Unit Type	
		TT-SMDC Product F	amily	TT-SMDC Pro	oduct Family	2022-	10-06					326.1			Each	
Alternate Recommend				Alternate Item			tem Co	Comments								
Manufacturing Proce	ss In	formation				•										
Terminal Plating / Grid Array Material Terminal			Terminal B	Base Alloy J-STD-020 MSL R		ating Peak Proces		ess Body Tempera		rature Max Time at P		Peak Temperature 1		Number of Reflow Cycles		
Matte Tin (Sn) Kovar Comments					1		245			10 secon			econds	2		

Save the fields in his form to a file	Export Data	Import fields from a file into this form	Import Data	Clear all of the fields on this form	Reset Form	Lock the fields on this form to prevent change	Lock Supplier Fields						
RoHS Material Com	position Declaration	n				Declaration Type *	Simplified						
OHS Directive 2002/95/EC ROHS Definition: Quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium, Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE) and quantity limit of 0.01% by mass (100 PPM) of homogeneous material for Cadmium													
te that Supplier completes this upplier may have relied on info upplier agrees that, at a minim itten agreement with respect t	s form. Supplier acknowledges the rmation provided by others in colum, its suppliers have provided c	hat Company will rely on this completing this form, and that Supertifications regarding their cond conditions of that agreement,	ertification in determining the opplier may not have independ attributions to the part, and tho	compliance of its products with ently verified such information se certifications are at least as	n European Union member state . However, in situations where S comprehensive as the certificati	laws that implement the RoHS Dir upplier has not independently ver on in this paragraph. If the Comp	its knowledge and belief, as of the ective. Company acknowledges that ified information provided by others, any and the Supplier enter into a Supplier's liability and the Company's						
RoHS Declaration * 3	- Item(s) does not contain Rol	dS restricted substances per	the definition above except	for lead in solders and selec	eted exemptions, if any	Supplier Acceptance * Ac	cepted						
xemptions: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration bove and choose all applicable exemptions.													
Exemption List Version	1												
-													
Declaration Signat	ure												
-	e all of the required field red by the Requester) ar	. •				wn. This will display the	signature area. Digitally sign						

Supplier Digital Signature YG Jiao

数字签名者: YG Jiao DN: cn=YG Jiao, o=RAMI TECHNOLOGY USA LLC, ou=QA, email=yglao@amiltechnology.com, c=CN 日期: 2013.08.27 09:46:08+08*00*

Homogeneous Material Composition Declaration for Electronic Products

Subltem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Line Functions: +I Inserts a New Item /SubItem +M Inserts a new Material +C Inserts a new Substance Category +S Inserts a new Substance - Deletes the element line

	Item/SubItem		Homogeneous	Weight	Unit of		Lavel	Substance Category			Substance	CAS	Evennt	Weight	Unit of	Tolerance		PPM
	Name		Material	weight	Measure		Level	Substance Category			Substance	CAS	Exempt	weight	Measure	-	+	PPIVI
+1 -1	TT-SMDC	+M -M	CAP	104.402	mg	+C -C	Supplier	C7251R	+S	-s	Fe	7439-89-6		0.009	mg			
									+S	-S	Cu	7440-50-8		59.994	mg			
									+S	-S	Mn	7439-96-5		0.122	mg			
							_		+S	-S	Zn	7440-66-6		17.3	mg			
						+C -C	В	Nickel (external applic	+S	-S	Nickel	7440-02-0		26.977	mg			
		+M -M	Enclosure	43.165	mg	+C -C	Supplier	Header	+S	-S	Mn	7439-96-5		0.07	mg			
									+S	-S	Fe	7439-89-6		14.023	mg			
							_		+S	-S	Cr	7440-47-3		0.016	mg			
						+C -C	Supplier	Glass	+S	-S	SiO2	14808-60-7		10.75	mg			
						+C -C	Supplier	Terminal	+S	-S	Со	7440-48-4		1.488	mg			
						+C -C	Supplier	Plating	+S	-S	Cu	7440-50-8		0.096	mg			
									+S	-S	Sn	7440-31-5		3.116	mg			
						+C -C	А	Lead/Lead Compound	+S	-S	Lead	7439-92-1	7a. Lead	3.35	mg			
						+C -C	В	Nickel (external applic	+S	-S	Nickel	7440-02-0		10.256	mg			
		+M -M	Blank	7.879	mg	+C -C	Supplier	Quartz	+S	-S	SiO2	7631-86-9		4.964	mg			
						+C -C	Supplier	Electrode	+S	-S	Ag	7440-22-4		2.915	mg			
		+M -M	Plastic mold	122.5	mg	+C -C	Supplier	Epoxy compound	+S	-S	SiO2	14808-60-7		86.975	mg			
									+S	-S	Epoxy Resin	85954-11-6		12.25	mg			
									+S	-S	Phenol Resin	61788-97-4		11.622	mg			
									+S	-S	Flame Retardent	1332-07-6		6.125	mg			
									+S	-S	Pigment	01333-86-4		3.078	mg			
								,	+S	-S	Coupling Agent	2530-83-8		2.45	mg			
		+M -M	Lead Frame	48.15	mg	+C -C	Supplier	Metal Frame	+S	-S	Cu	7440-50-8		29.882	mg			

+S -S Zn	7440-66-6		14.994	mg								
+(C -C Supplier	Surface coating		+S	-s	Sn		7440-31-5	3.274	mg		